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HG

**CHEMICAL INDUSTRY STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

HG/T 6240-2023

Copper chloride dihydrate for electroplating

电镀用二水合氯化铜

(English Translation)

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This standard specifies the requirements, test methods, inspection rules, markings, labels and accompanying documents, packaging, transportation and storage of copper chloride dihydrate for electroplating. This standard applies to copper chloride dihydrate for electroplating. Note: This product is mainly used as an additive for electroplating copper, electroplating brass, and electroless copper plating processes.